

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT						
NATURE OF CONVEYANCE:	ASSIGNMENT						
CONVEYING PARTY DATA							
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Sairam Agraharam</td> <td>03/14/2006</td> </tr> <tr> <td>Rahul N. Manepalli</td> <td>03/13/2006</td> </tr> </tbody> </table>		Name	Execution Date	Sairam Agraharam	03/14/2006	Rahul N. Manepalli	03/13/2006
Name	Execution Date						
Sairam Agraharam	03/14/2006						
Rahul N. Manepalli	03/13/2006						
RECEIVING PARTY DATA							
Name:	Intel Corporation						
Street Address:	2200 Mission College Blvd.						
City:	Santa Clara						
State/Country:	CALIFORNIA						
Postal Code:	95052-8119						
PROPERTY NUMBERS Total: 1							
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>11301557</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	11301557		
Property Type	Number						
Application Number:	11301557						
CORRESPONDENCE DATA							
Fax Number:	(612)677-3572						
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>							
Phone:	503-712-3206						
Email:	chartness@cpaglobal.com						
Correspondent Name:	Kerry Tweet						
Address Line 1:	c/o CPA Global, P.O. Box 52050						
Address Line 4:	MINNEAPOLIS, MINNESOTA 55402						
ATTORNEY DOCKET NUMBER:	P22459						
NAME OF SUBMITTER:	Christine Hartness						

CH \$40.00 11301557

Total Attachments: 4
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Applicant's Reference No.: P22459

ASSIGNMENT

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, we, the undersigned:

Sairam Agraharam; Rahul N. Manepalli

hereby sell, assign, and transfer to:

Intel Corporation

a corporation of Delaware, having a principal place of business at 2200 Mission College Boulevard, Santa Clara, California, 95052-8119 USA ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all foreign countries, in and to, any and all inventions and improvement that are disclosed in the application for the United States patent filed on December 13, 2005, and assigned Application No. 11/301,557 and is entitled:

INTEGRATED CIRCUIT DEVICES INCLUDING COMPLIANT MATERIAL UNDER BOND PADS AND METHODS OF FABRICATION

and in and to said application and all design, utility, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and all other patent applications that have been or shall be filed in the United States and all foreign countries on any of said inventions and improvement; and in and to all original and reissued patents that have been or shall be issued in the United States and all foreign countries on said inventions and improvements; and in and to all rights of priority from the filing of said United States application;

agree that said Assignee may apply for and receive a patent for said inventions and improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all design, utility, continuing, continuation-in-part, substitute, renewal, reissue, and all other patent applications on any and all said inventions and improvements; execute all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors, assigns, and legal representatives all facts known to the undersigned relating to said inventions and improvements and the history thereof; and generally assist said Assignee, its successors, assigns, and legal representatives in securing and maintaining proper patent protections for said inventions and improvements and for vesting title to said inventions and improvements, and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Applicant's Reference No.: P22459

ASSIGNMENT

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hereby sell, assign, and transfer to:

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and in and to said application and all design, utility, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and all other patent applications that have been or shall be filed in the United States and all foreign countries on any of said inventions and improvement; and in and to all original and reissued patents that have been or shall be issued in the United States and all foreign countries on said inventions and improvements; and in and to all rights of priority from the filing of said United States application;

agree that said Assignee may apply for and receive a patent for said inventions and improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all design, utility, continuing, continuation-in-part, substitute, renewal, reissue, and all other patent applications on any and all said inventions and improvements; execute all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors, assigns, and legal representatives all facts known to the undersigned relating to said inventions and improvements and the history thereof; and generally assist said Assignee, its successors, assigns, and legal representatives in securing and maintaining proper patent protections for said inventions and improvements and for vesting title to said inventions and improvements, and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Applicant's Reference No.: P22459

Each Inventor: Please Sign and Date Below:

Date

Name: Sairam Agraharam

Date

March 13 09

Name: Rahul N. Manepalli